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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. PENDSE, *et al.*

Application No.: 10/084,787

Filed: February 25, 2002

Title: **Super-thin high speed flip chip package**

)
) Examiner: Alexander O. WILLIAMS
)
) Group Art Unit: 2826
)
) Date: December 3, 2002
)
) CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on December 3, 2002.

Signed

Linda Shaw

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

AMENDMENT

Dear Sir:

Responsive to the Office Action mailed July 3, 2002, kindly amend the application as follows.

In the Claims

Delete claim 5 without prejudice or disclaimer.

Please amend claims 1 and 2 as shown on the attached "Attachment under Rule 1.121", as follows.

A | 1. (Amended) A chip scale integrated circuit chip package comprising a die mounted by flip chip interconnection to a first surface of a package substrate, wherein the flip chip interconnection comprises solid state connections of interconnect bumps affixed to the die with interconnect pads on the first surface of the substrate; and second level interconnections formed on the first surface of the package substrate.

2. (Amended) The package of claim 1 wherein the die is provided with interconnection bumps affixed to an arrangement of connection sites in a first surface of the die, and the flip chip